

METHOD FOR MANUFACTURING FILLING PLANARIZATION FILM AND METHOD FOR MANUFACTURING ELECTRONIC DEVICE

ABSTRACT

A method for manufacturing a filling planarization film, the method including: a first coating step of applying a first coating liquid, containing a polyamine and a first solvent, to a region including a recessed part of a member having the recessed part, to fill the first coating liquid into the recessed part; and a second coating step of applying a second coating liquid, containing an organic substance having two or more carboxyl groups and a second solvent having a boiling point of 200°C or less and an SP value of 30 (MPa)^{1/2} or less, to the region including the recessed part of the member into which the first coating liquid has been filled.

Fig. 1